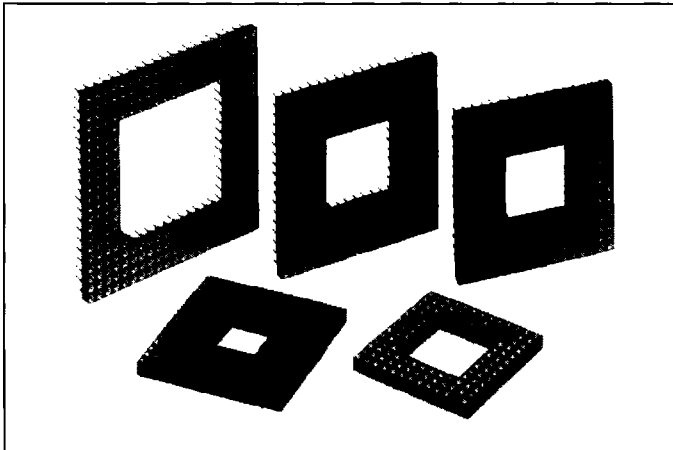


# HIGH DENSITY Pin Grid Array Sockets



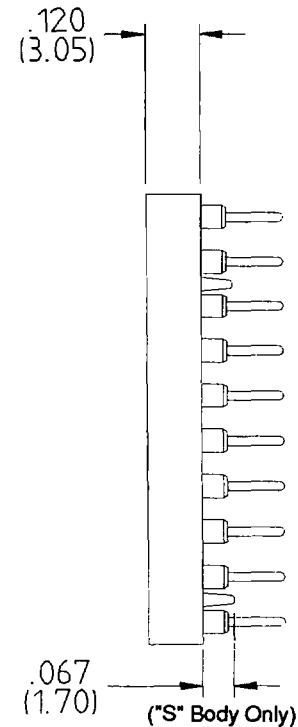
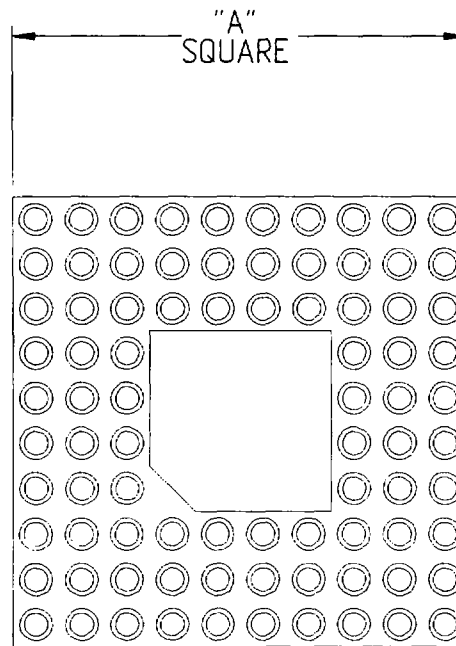
## PGA SERIES



- High temp molded insulator body
- Stand-offs available to eliminate intermittent solder connections
- Precision screw machine sockets for high reliability
- Available with solder, wire wrap and press-fit tails
- Available with "Ultra Low Force" 6-finger contact

SOCKETS

Grid Size	Dimension A
8 x 8	.800" (20.32)
9 x 9	.900" (22.86)
10 x 10	1.000" (25.40)
11 x 11	1.100" (27.94)
12 x 12	1.200" (30.48)
13 x 13	1.300" (33.02)
14 x 14	1.400" (35.56)
15 x 15	1.500" (38.10)
16 x 16	1.600" (40.64)
17 x 17	1.700" (43.18)
18 x 18	1.800" (45.72)
19 x 19	1.900" (48.26)
20 x 20	2.000" (50.80)
21 x 21	2.100" (53.34)



### Materials:

**Body:** High temp, black polyester, glass-filled  
**Contacts:** Beryllium Copper  
**Shell:** Half Hard Brass

### Acceptable Pin Sizes:

**Diameter:** .016" - .021" (.41 - .53)  
**Length:**  
**S, US, SL, USL, E275,**  
**E350, E1, CP:** .110" - .150" (2.79 - 3.81)  
**E2, WB:** .110" - .165" (2.79 - 4.19)  
**SP138:** .110" - .175" (2.79 - 4.45)

### Mounting Information:

**Solder Tail &**  
**Wire Wrap:** = .040" ± .002" (1.01 ± .05) PCB  
**Press-Fit:** = .037" - .042" (.93 - 1.07) DIA  
 finished PTH

**Agency Approvals:** #E73746

### Performance Characteristics:

**Low Force (All Lead Styles Except US & USL)**  
**Insertion Force:** 3 ounces\* max per contact  
**Withdrawal Force:** .7 ounce\* min per contact  
**Ultra Low Force (US & USL Lead Styles)**  
**Insertion Force:** 1.7 ounces\* max per contact  
**Withdrawal Force:** .35 ounce\* min per contact  
 \*using .018" diameter pin

**Capacitance:** 1 picofarad maximum  
**Insulation Resistance:** 5000 megohms minimum  
**Dielectric Withstanding Voltage:** 500 volts AC  
**Current Rating:** 1 Ampere  
**Flammability:** UL 94V-0  
**Temperature Range:** -65°C to + 125°C

### Plating Description:

**Suffix: TG =** 10 μinch (.254 μm) minimum Gold on contact area.  
 200 μinch (5.08 μm) minimum Tin/Lead on terminal area.  
**TG30 =** 30 μinch (.762 μm) minimum Gold on contact area.  
 200 μinch (5.08 μm) minimum Tin/Lead on terminal area.  
**TT =** 150 μinch (3.81 μm) minimum Tin/Lead on contact area.  
 200 μinch (5.08 μm) minimum Tin/Lead on terminal area.

All options include an Underplate of 50 μinch (1.27 μm) minimum Nickel.

## How To Order PGA Series

**PGA — 132 A H 3 — X — XX**

Number of Contacts  
(See pages 114-117)

Loading Pattern Code  
(See pages 114-117)

Body Specification:

H = High Temp  
S = High Temp with Stand-offs  
M = Standard Polyester  
(8x8, 9x9 & 10x10 Full Grid)

Plating Code: Specify  
TG, TG30, TT

Lead Style

## Lead Style

